ABSTRACT

ALUMINUM CAP WITH ELECTROLESS NICKEL/IMMERSION GOLD

A method of forming a solder bump (and the resulting solder bump structure), comprising the following steps. A structure having a metal bond pad formed thereover is provided. A patterned cover layer is formed over the structure. The patterned cover layer including an opening exposing a portion of the metal bond pad. The patterned cover layer opening including side walls. A metal cap layer is formed over at least the exposed portion of the metal bond pad and the patterned cover layer side walls. A solder bump is formed over the metal cap layer.

FIGURE 6